

POWER DISSIPATION (SOT-23-5)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board.

This specification is based on the measurement at the condition below:

(Power Dissipation (SOT-23-5) is substitution of SOT-23-6.)

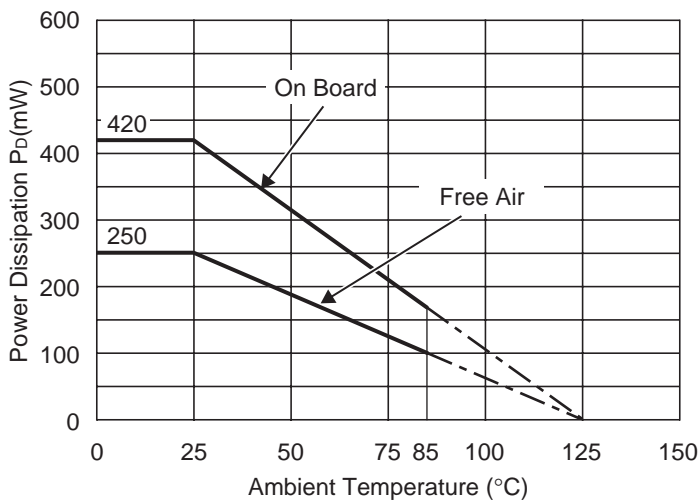
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

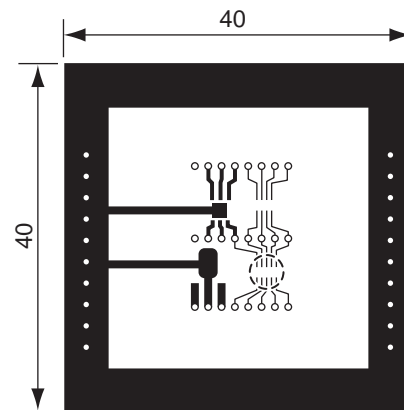
Measurement Result

($T_{opt}=25^{\circ}C$, $T_{jmax}=125^{\circ}C$)

	Standard Land Pattern	Free Air
Power Dissipation	420mW	250mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.42W=238^{\circ}C/W$	400 $^{\circ}C/W$



Power Dissipation



Measurement Board Pattern

○ IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN

